

PATENTS ONLY (ref OG 7/28/92)

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original document or copy thereof.

1. Name of Party(ies) conveying an interest:
- Toshiya UOZUMI 06/29/2005
Yasuyuki KIMURA 06/29/2005
Hirotaka OSAWA 07/04/2005
Satoru YAMAMOTO 06/29/2005
Robert Astle HENSHAW 10/03/2005
2. Name and Address of Party(ies) receiving an interest:
1. RENESAS TECHNOLOGY CORP.
4-1 Marunouchi 2-chome
Chiyoda-ku, Tokyo, JAPAN
&
2. TTPCOM LIMITED
Melbourn Science Park
Cambridge Road
Melbourn, Royston
Hertfordshire SG8 6EE, United Kingdom
3. Description of the interest conveyed: Assignment
4. Application number(s) or patent number(s).
- Additional sheet attached? Yes XXX No
- If this document is being filed together with a new application,
the execution date of the application is:
DATE
- A. Patent Application No.(s) B. Patent No.(s)
- 11/181,876
5. Name and address of party to whom correspondence concerning document should be mailed:
- Mattingly, Stanger, Malur & Brundidge, P.C.
1800 Diagonal Road, Suite 370
Alexandria, Virginia 22314
6. Number of applications and patents involved: One
7. Amount of fee enclosed or authorized to be charged: \$40.00
8. The Commissioner is hereby authorized to charge Deposit Account No. 50-1417 if no credit card payment form is attached.

DO NOT USE THIS SPACE

9. Execution date of attached document: 6/29/2005, 7/4/2005 & 10/3/2005
10. To the best of my knowledge and belief, I declare under penalty of perjury under the laws of the United States of America that the foregoing information is true and correct and that any attached copy is a true copy of the original document.

Daniel J. Stanger
Name of Person Signing

Signature _____

December 21, 2006
Date

Total number of pages being submitted: 1

SEP-30-05 02:33PM FROM- MATTINGLY, STANGER, MALUR & BRUNDIDGE + 703 884 1157

T-046 P.008/008 F-560

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me a citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 4-1 Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan, and TTPCom Limited, a corporation organized under the laws of United Kingdom, located at Melbourn Science Park, Cambridge Road, Melbourn, Royston, Hertfordshire SG8 6EE, United Kingdom, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., and TTPCom Limited, their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A COMMUNICATION SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND A WIRELESS COMMUNICATION SYSTEM

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., and TTPCom Limited, their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp., and TTPCom Limited.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Toshiya UOZUMI</u> Toshiya UOZUMI	<u>29 / June / 2005</u>
2)	<u>Yasuyuki KIMURA</u> Yasuyuki KIMURA	<u>29 / June / 2005</u>
3)	<u>Hirotaaka Osawa</u> Hirotaaka OSAWA	<u>4 / July / 2005</u>
4)	<u>Satoru Yamamoto</u> Satoru YAMAMOTO	<u>29 / June / 2005</u>
6)	<u>Robert Astle Henshaw</u> Robert Astle HENSHAW	<u>3 / October / 2005</u>
8)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____